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<b>TITLE:</b> 783 I/O FC PBGA 29 X 29 PKG 1 MM PITCH WITH FLAT PLATE LID AND CAP ZONES	DOCUMENT NO: 98ASA10525D      REV: H	
	STANDARD: NON-JEDEC	
	SOT1623-5      15 JAN 2016	



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

7. ~~FC CBGA (CERAMIC) PACKAGE CODE: 5112~~ DELETED  
FC PBGA (PLASTIC) PACKAGE CODE: 5301

8. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

9. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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